MTCA.4 Tutorial Basics

Introduction in xTCA



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Agenda

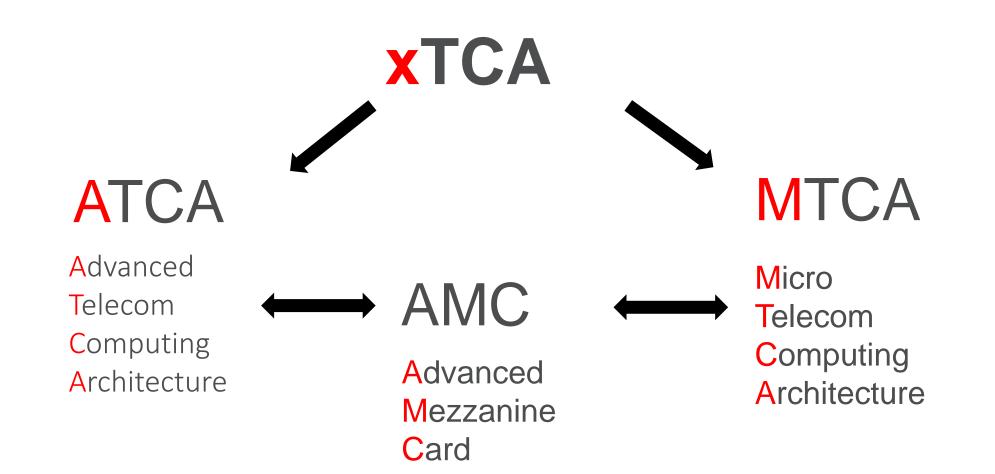
- What is xTCA?
- Specifications Overview
- ATCA Features
- > AMC Features
- MTCA.0 Features

> MTCA.4

- Initial Requirements
- Mechanical Features
- Module sizes
- Keying
- Backplane
- Management extensions compared to MTCA.0
- Hot Swap Transition States
- Cooling
- Redundancy
- MTCA.4.1



is xTCA?





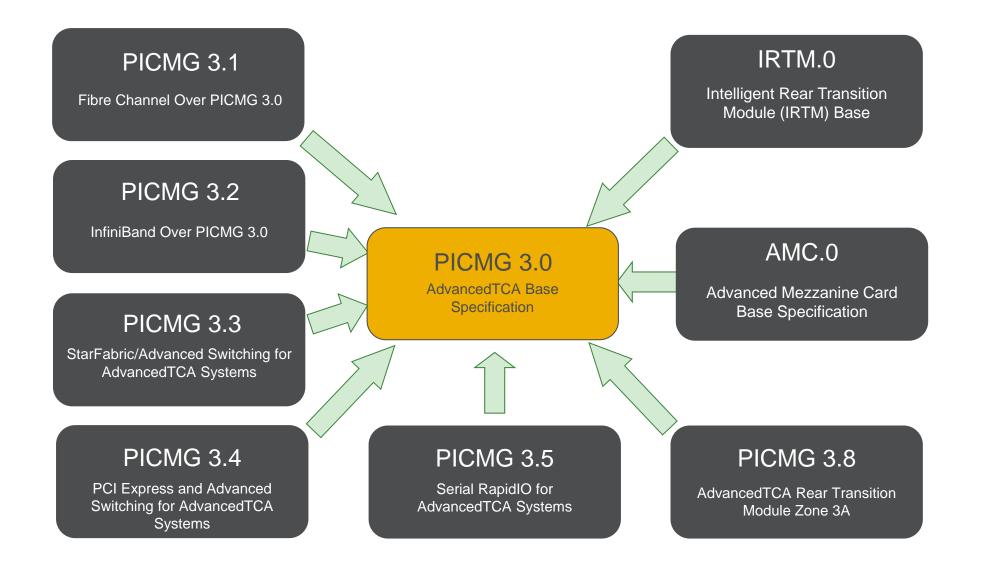




Overview

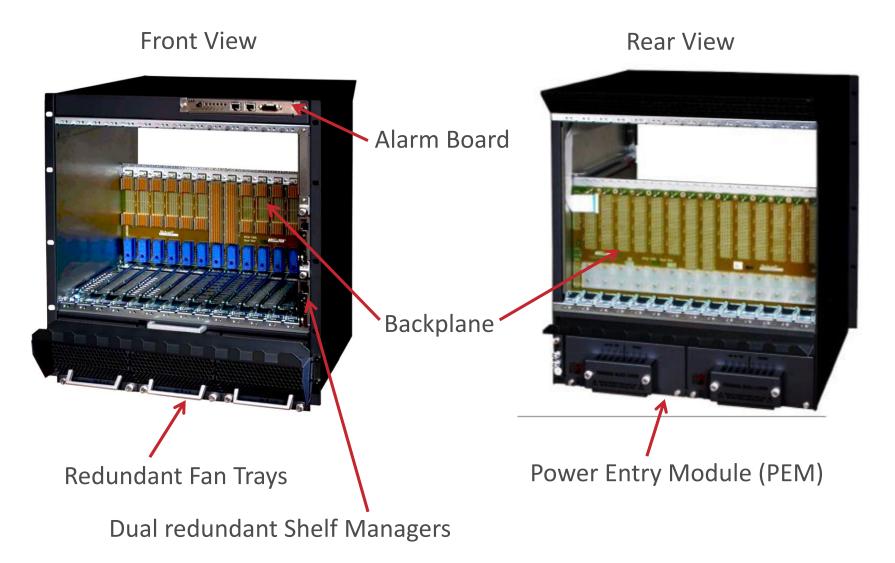
- Specification initially targeted to the Telco Industry
- Features required for the new standard:
- System Availability 99.999% (~5 min/yr)
- System throughput to 2 Tb/s (full mesh)
- Port data rate to 40 Gb/s (4 x 10Gb/s), today 100Gb/s
- Management, monitoring and control!
- Software infrastructure providing API's, etc!
- Introduced in 2002







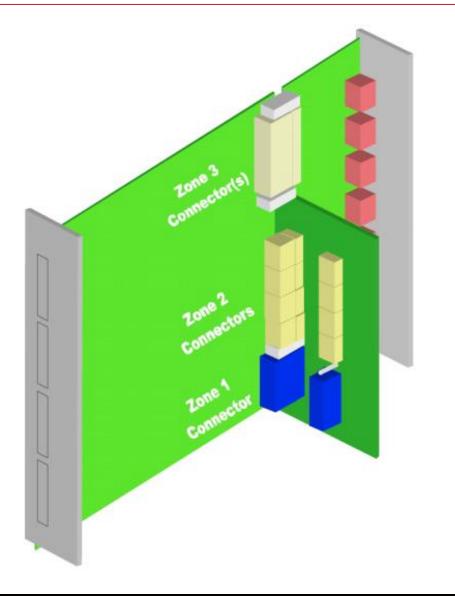
ATCA Shelf Elements





ATCA Shelf Elements

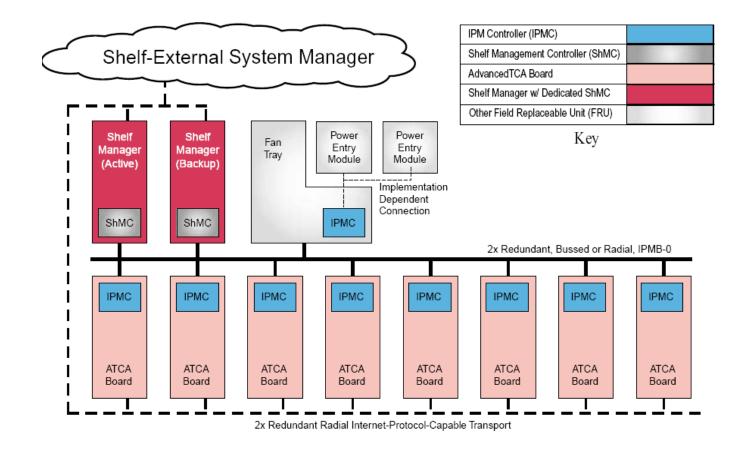
- Board size and connectors
- Front board size 8U x 280
- Rear board (RTM) size 8U x 70 mm
 - Connects directly to front board
- Board width 6HP (1.2")
- Alignment/Key pins
- Zone 1: Management and Power
- Zone 2: Base Interface and Fabric Interface
- Zone 3: Interface to RTM





ATCA Management

- Dedicated Shelf Management Controller (ShMC)
- > ATCA Boards with IPMC
- Protocol IPMI (Physical layer I2C-Bus)
- Intelligent and Managed FRUs
- Bused or Radial IPMB



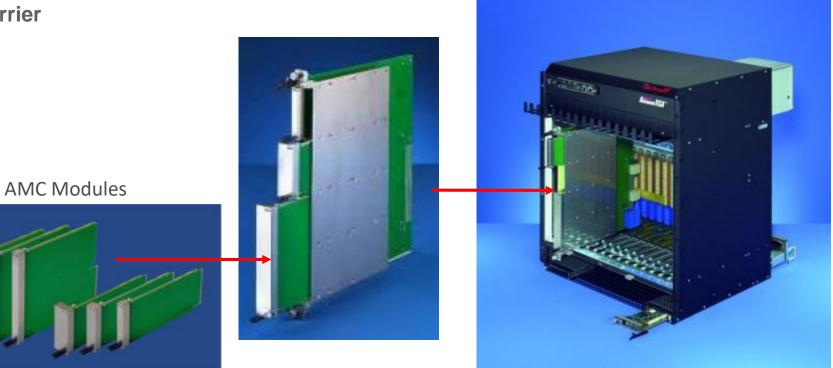






AMC Modules

- Initially developed as function extension for ATCA Boards
- Fully integrated into the ATCA IPMI management structure
- Plugged into a so called ATCA Carrier
- Hot Swap capability



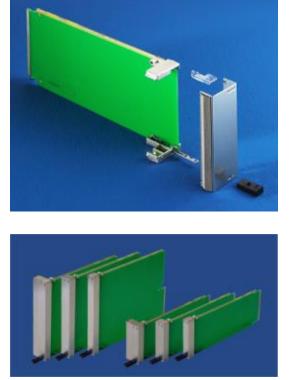


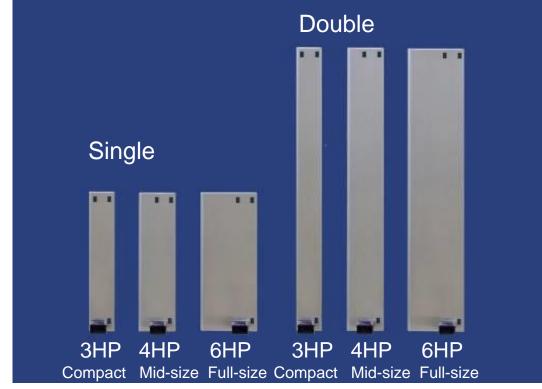
AMC Modules

> AMC Module Sizes

> 6 Standard Sizes:

- Depth dimension: 180 mm
- Width dimensions: Single and Double
- Height dimensions: Compact, Mid-size and Full-size

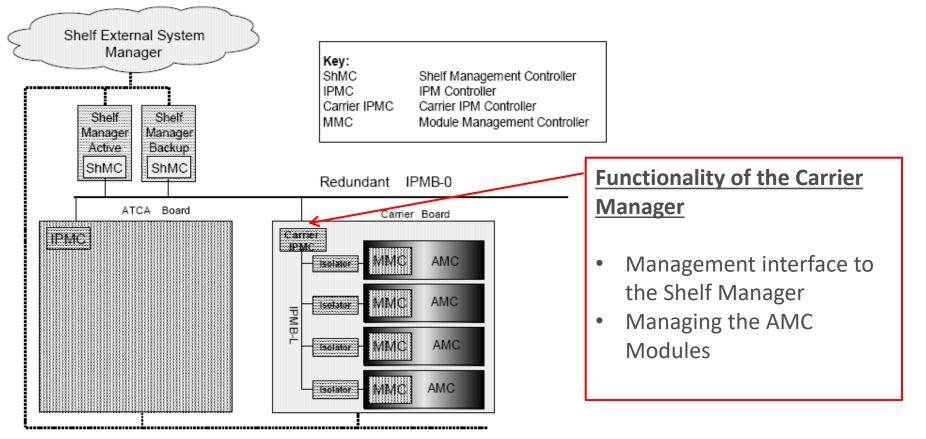






AMC Modules

> Carrier IPMC represents the MMC on the AMC as a FRU to the Shelf Manager



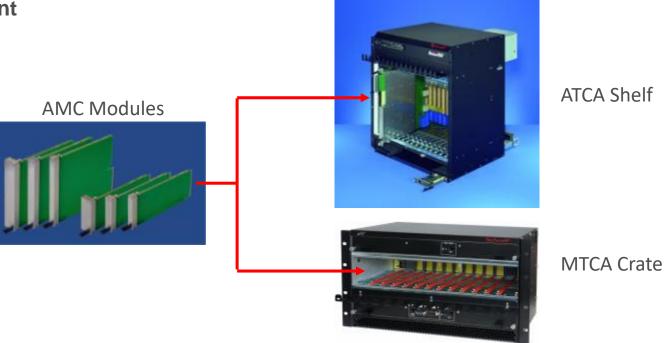
2x Redundant Radial Internet Protocol -Capable Transport







- > The basic idea of MTCA is to have a shelf that contains just AMC modules
- Backplane directly accepts AMC modules
- > AMCs are interchangeable between ATCA and MTCA
- > The infrastructure of a ATCA Carrier was adapted into the MTCA crate (power, management, switching)
- > No rear I/O, power input and all outputs to the front



ATCA Shelf

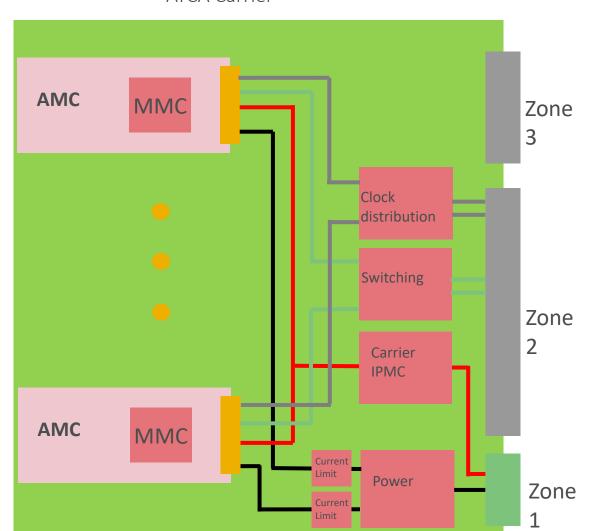


- As MicroTCA does not use a Carrier board, the power, management, clock distribution and switching functionality must be realized onto another device
- Management Module: MCH (MTCA Carrier Hub)
 - IPMI management
 - clock distribution / generation
 - Switching functionality
 - JTAG slave / master
 - Redundant MCHs

Power Module

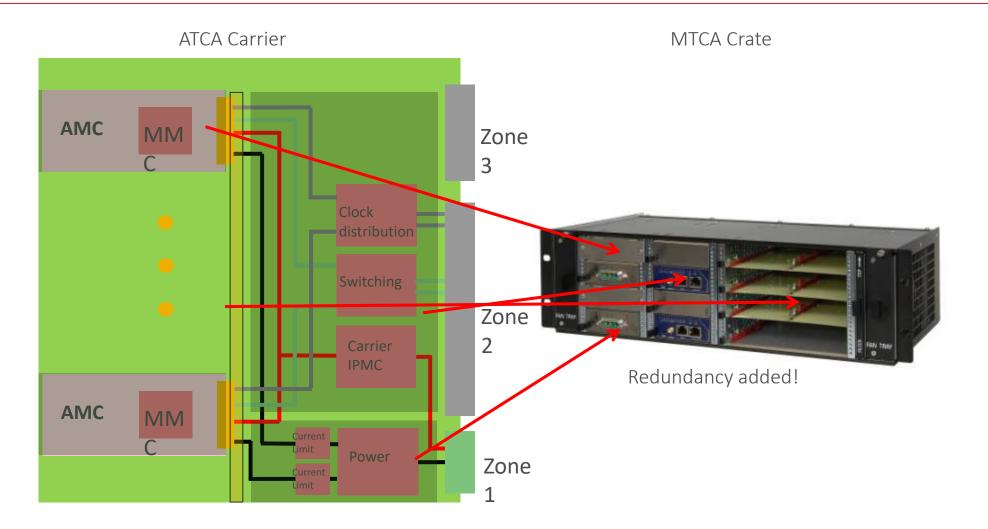
- 12V Payload Power
- 3.3V Management Power
- Redundant power modules
- > Dedicated Slots for these modules are located in the MTCA crate





ATCA Carrier

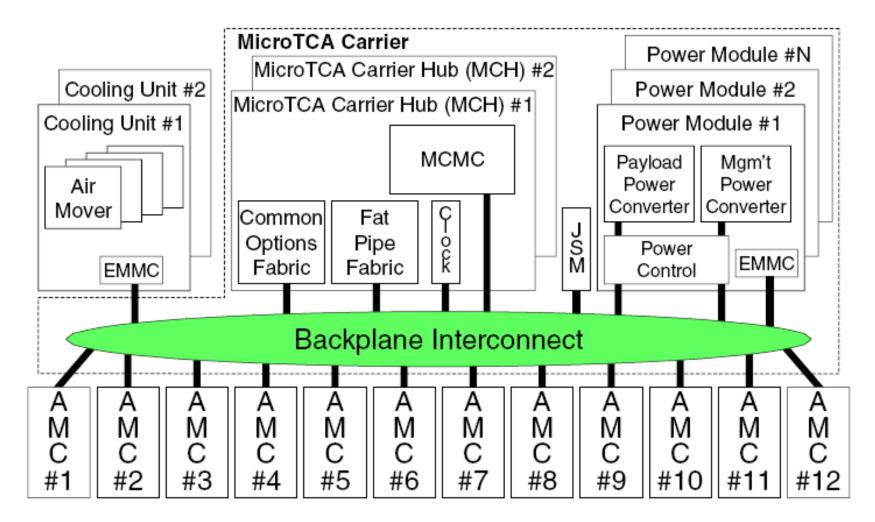








MicroTCA block diagram





Terms and Acronyms

MCH MicroTCA Carrier Hub

• Management and switching module

MCMC MicroTCA Carrier Management Controller

• Physical IPMI controller on the MCH

> MMC Module Management Controller

• Physical IPMI controller on an AMC

EMMC Enhanced MicroTCA Carrier Management Controller

• Physical IPMI controller on a Cooling Unit and on Power Module

> IPMB-0 Intelligent Platform Management Bus 0

• Logical IPMB, physically divided into redundant IPMB-A and IPMB-B

> IPMB-L IPMB-Local

• IPMI link between MCH and AMCs







> Why were extensions needed to the existing MicroTCA specifications?

> No Rear Transition Module (RTM) defined for MicroTCA

• Requirement for a large number of I/O cables. It makes sense to connect them to the rear of the chassis

Special clock and trigger topology

MicroTCA.0 specifies 3 Clocks and AMC.0 R2.0 specifies 4 Telecom and 1 Fabric Clock on the AMC Module. Physics applications
typically need additional Clocks and Triggers

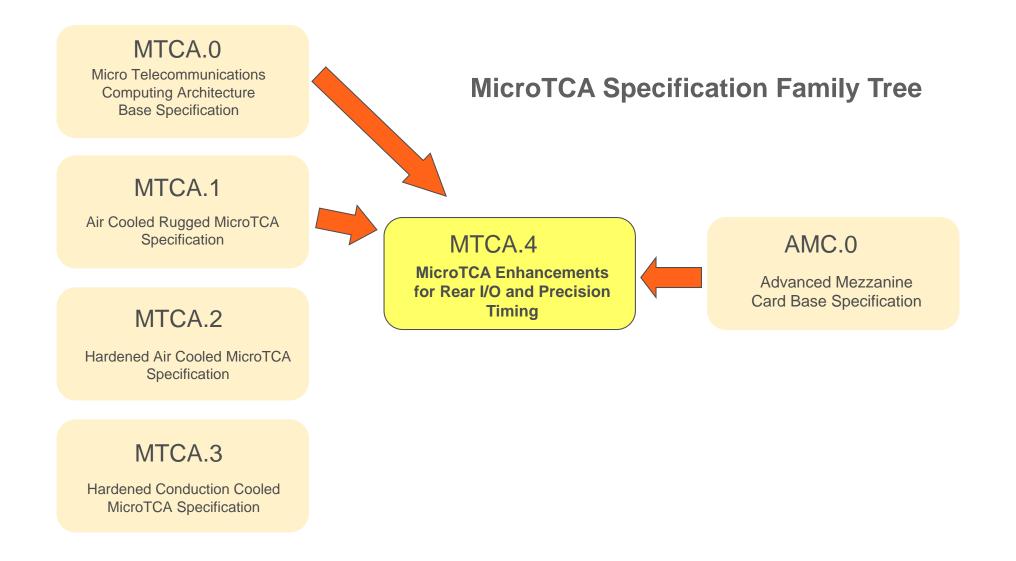
Sophisticated requirements for the clock and trigger accuracy

• MicroTCA / AMC defines typical telecom clock signals corresponding to PCIe values. Trigger signals are not specified



- Requirements for mechanics and sizes
- > AMC Module size: Double, Mid-size
 - In a 19" wide crate the AMC module size doube mid-size allows front configuration of:
 - max. 2 MCHs
 - max. 4 power units
 - max. 12 AMCs
- Large MicroRTM real estate
 - MicroRTM size approximately the size of the AMC (doubles depth of existing MTCA chassis)
- Use front panel mechanics based on Rugged MicroTCA (MTCA.1)
 - Need to mechanically attach a module to avoid it being pushed-out by the corresponding module
 - Use Rugged MicroTCA retention device
- Reuse existing AMC front panels for the MicroRTM
- > Allowing mounting of mezzanine modules on the rear of the backplane
- > Optional zone 3 backplane
- Define the management of the system
- Suggest clocking and backplane topology







Typical MTCA.4 Crate



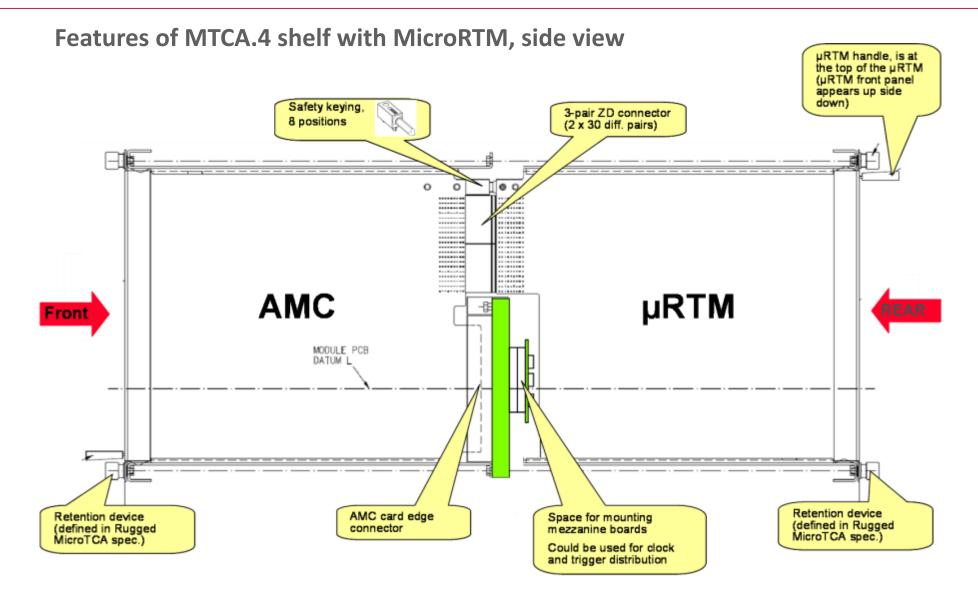
- 1 Upper Cooling Unit (CU1)
- 2 Lower Cooling
- 3 Air filter
- 4 ESD Wrist Strap Terminal
- 5 Cable Tray Unit (CU2)
- 6 Backplane
- 7 Card cage



- 8 Rear card cage
- 9 Cable Tray
- 10 Ground Terminal



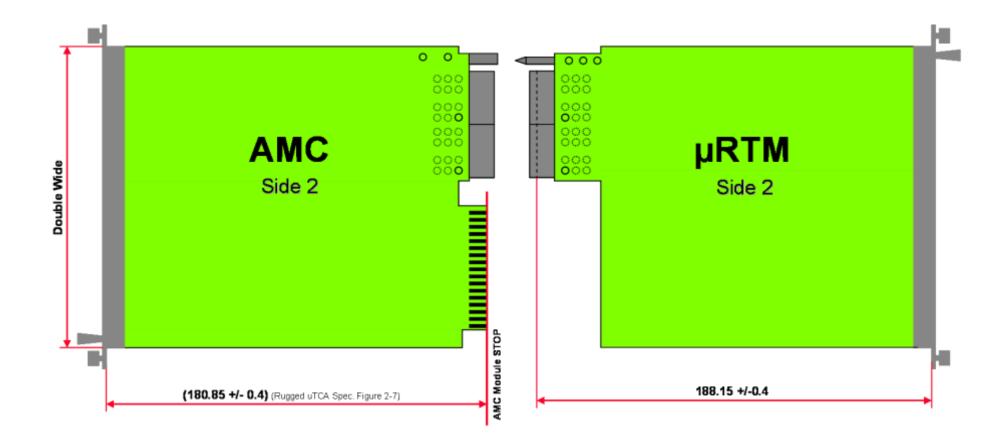








Module Sizes





Alignment and Keying

- Mechanical keying prevents a module from being inserted which is not electrically compatible and could cause damage
- Eight keying positions are implemented that define the electrical interface

N	A Rotation in	View into rear of AMC	View into rear of µRTM
	degrees	Receptacle	Post
1	0	•	•
2	45	lacksquare	
3	90	\bullet	
4	135		
5	180	Θ	
6	225	\mathbf{O}	•
7	270	Ð	
8	315	Ø	
0	NA	0	\bullet

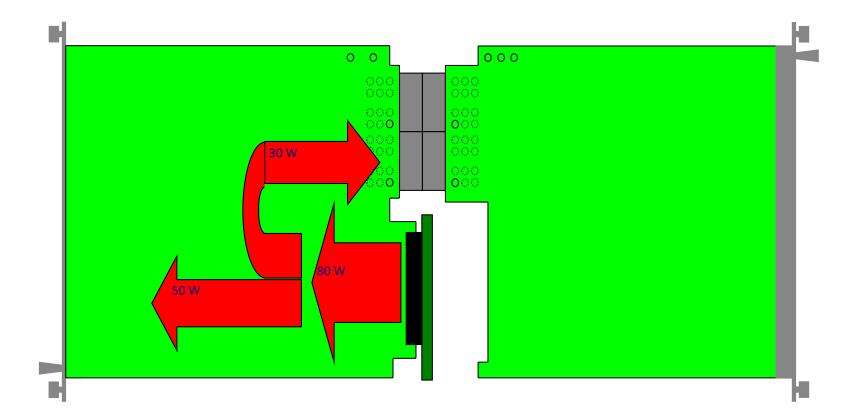
Ν	Data Signal in Volts	
1	LVDS	
2	$0 - \pm 1$	
3	>±1-±3.3	
4	>±3.3 - ±10	
5	>±10	
6	Reserved	
7	Reserved	
8	Reserved	



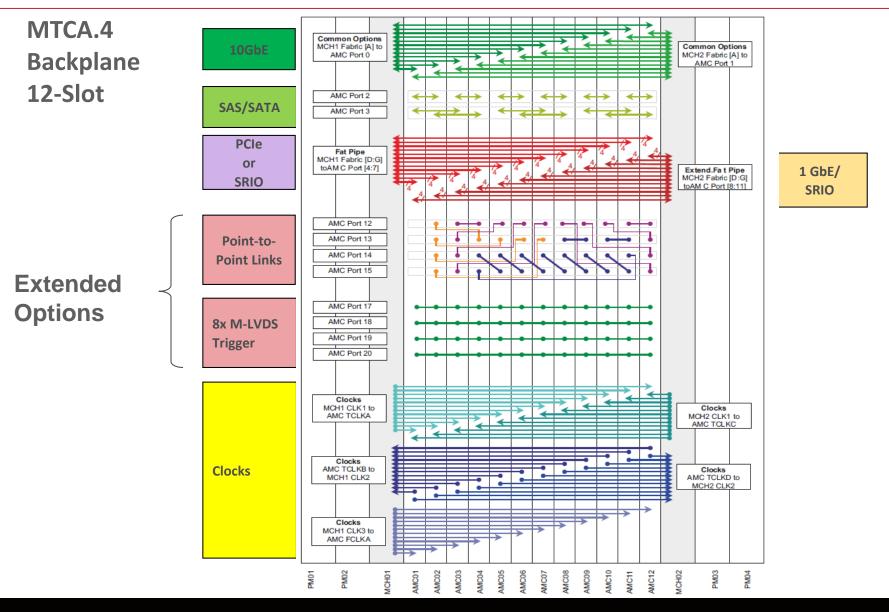


Front board and MicroRTM power distribution

- The total power for a slot (front board and RTM) is supplied through the front board AMC connector
- The MicroRTM power is supplied from the front board through the Zone 3 connectors
- Total available power for a slot is 80 Watts, the MicroRTM power is limited to 30 Watts
- The power required by the MicroRTM is subtracted from the power for the front board









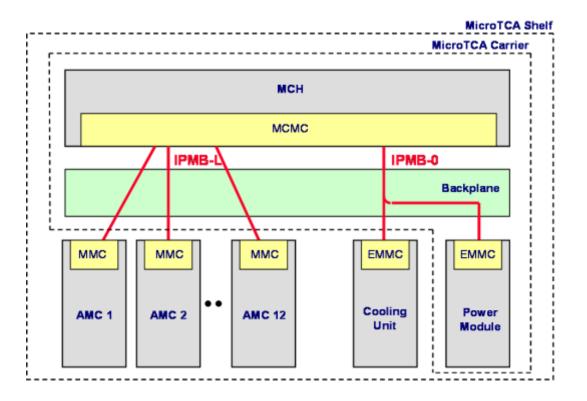
Management defined in AMC.0 / MTCA.0

IPMB-L

- Connects the MCMC on the MCH to the MMC on the AMC Modules
- Radial architecture

► IPMB-0

- Connects the MCMC on the MCH to the EMMC on the PM and CU
- Bused architecture





Management extensions in MTCA.4

IPMB-L

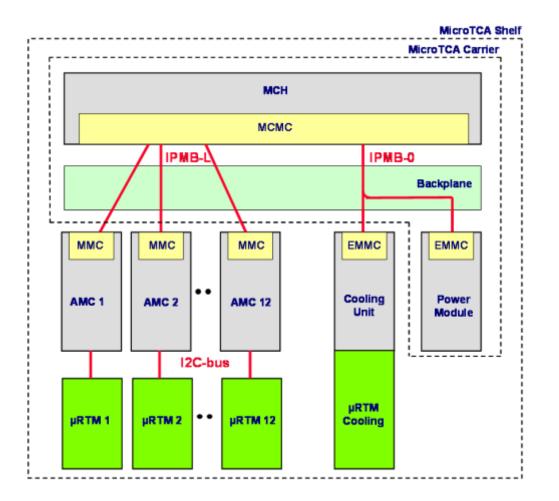
- Connects the MCMC on the MCH to the MMC on the AMC Modules
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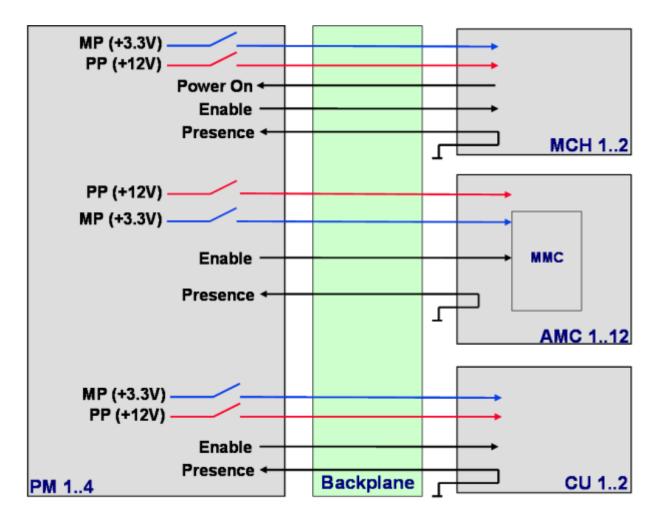
► I2C-Bus

- Connects the AMC to the μRTM
- The μRTM is treated as managed FRU of the AMC





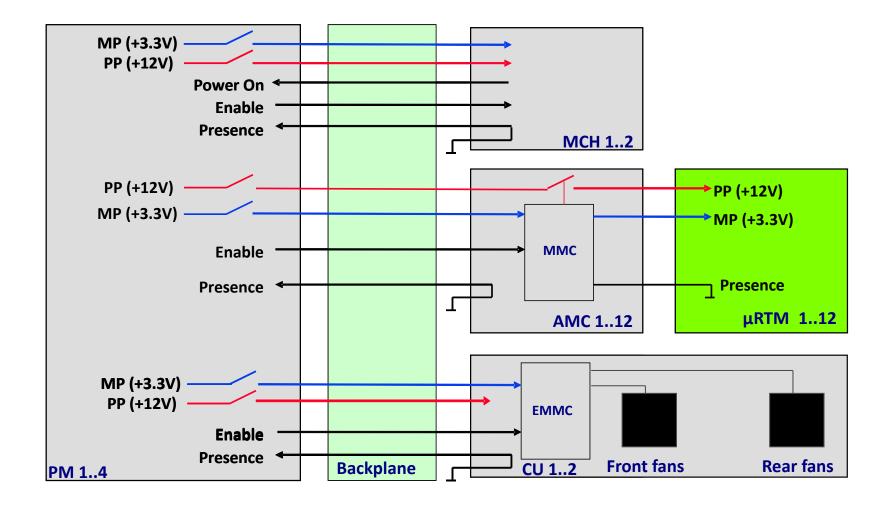
Control signals as defined per AMC.0 / MTCA.0







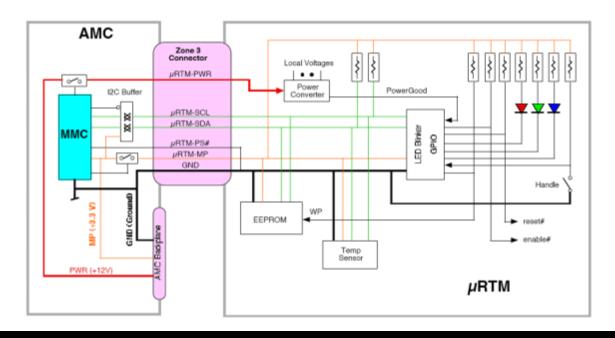
Additional RTM control signals for MTCA.4



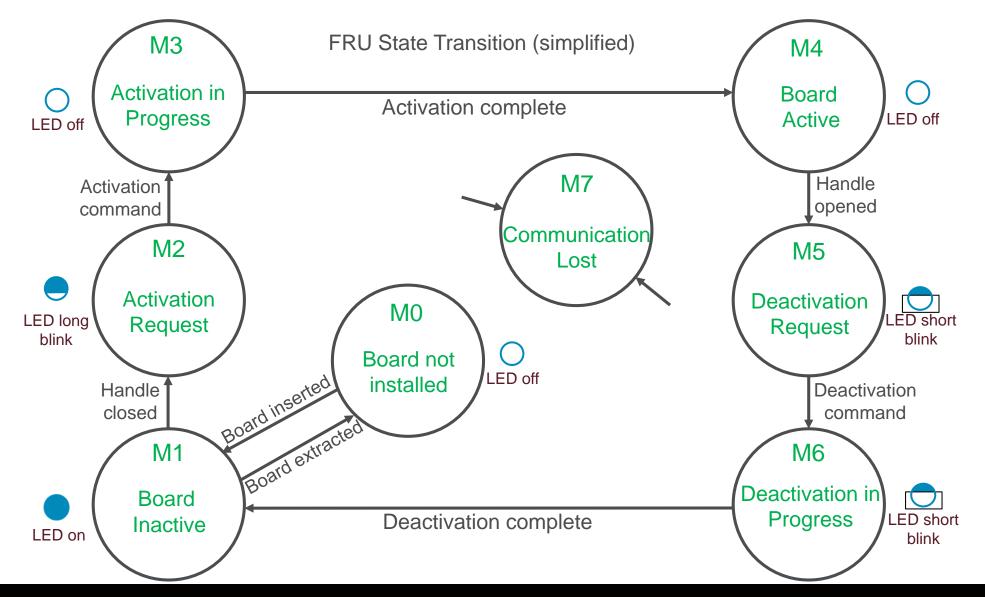


MicroRTM Management

- > A management interface is defined on the lower zone 3 connector
- Management and power signals:
 - µRTM-MP: Management Power for the EEPROM, Temp. Sensor and I/O Expander
 - µRTM-PWR: Payload power for the RTM
 - µRTM-PS#: RTM Presence signal, grounded on the RTM
 - μ RTM-SCL/SDR:I2C bus coming from the AMC MMC going to the RTM







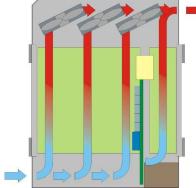


Cooling concepts

- The cooling concept depends on the installation situation of the chassis:
 - Front-to-rear air flow
 - Side-to-side air flow
 - Bottom-to-top air flow
 - Front-to-side air flow

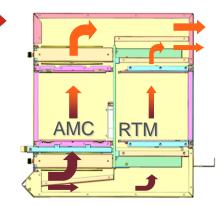
> Fan configuration:

- Push
- Pull
- Push-pull

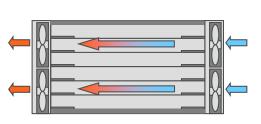


Pull configuration, Front-to-rear

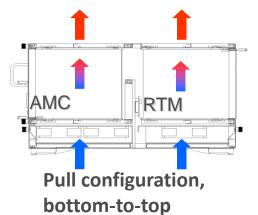




Push-Pull configuration Front to rear



Push-Pull configuration Side-to-side





Redundancy

- For high availability applications all modules are redundant:
- ➤ 2 x MCH
- > 4 x Power Module
- 2 x Cooling Unit

> IPMB-0:

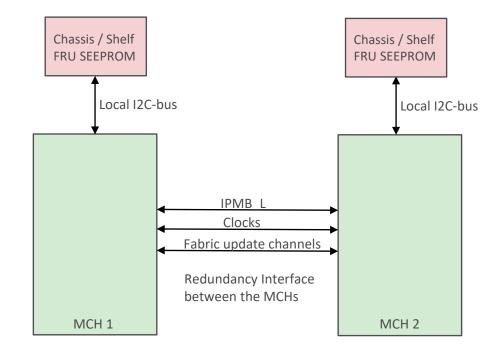
One logical bus divided into two physical busses: IPMB-A and IPMB-B





MCH Redundancy

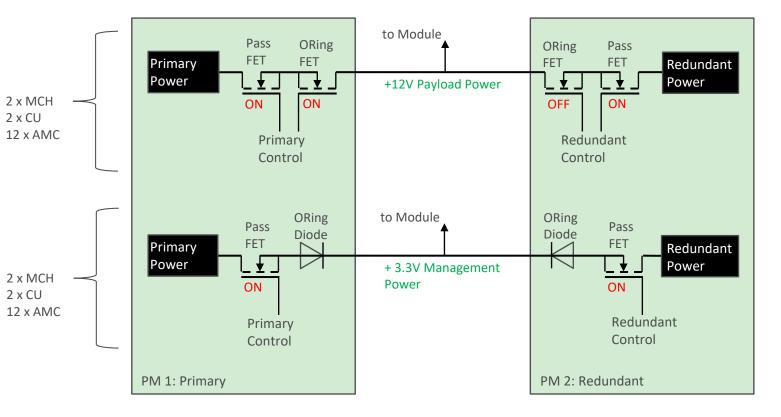
- Two MCH: One is Master, One is Redundant
- Redundant chassis / shelf FRU Information SEEPROM
- Redundancy Interface between the two MCH
- Redundancy defined in chassis / shelf FRU information





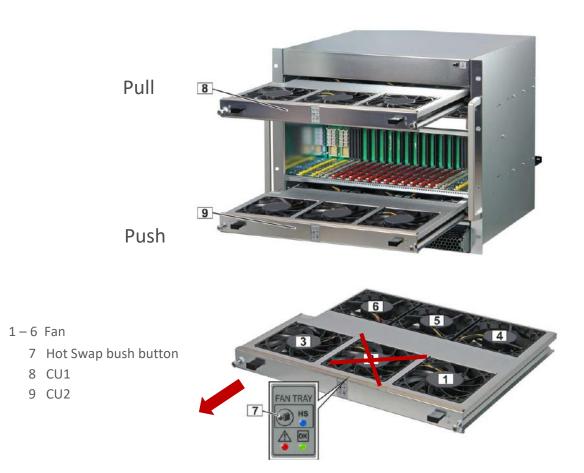
Power Module Redundancy

- > Up to 4 Power Modules per chassis
- Redundancy mode defined in shelf FRU file
- Individual power channel to each module and FRU





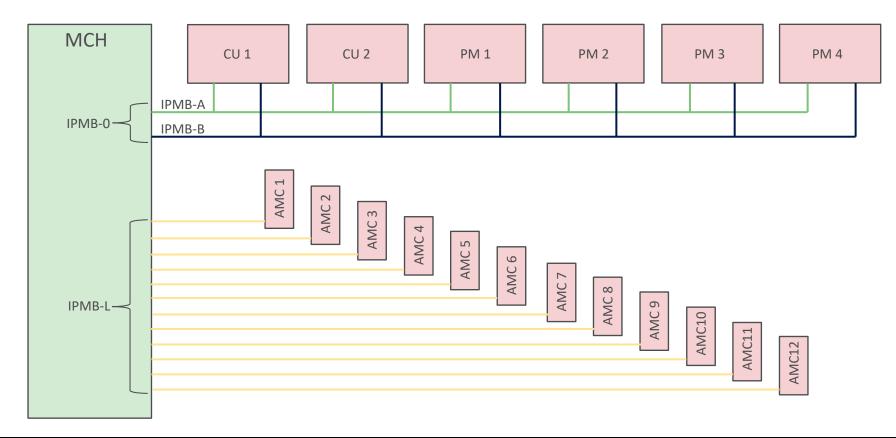
- Redundant Cooling Units in push-pull configuration
- > Scenario 1: fan failure
- Scenario 2: Cooling Unit replacement





IPMB redundancy

- Individual IPMB-L to each AMC
- Redundant logical IPMB-0 to PMs and CUs





MTCA.4 Chassis types

- > Various different MTCA.4 crates available:
 - Laboratory use
 - Fully redundant
 - Compact sizes
 - Small form factors
 - Different cooling concepts
 - Different backplane topologies













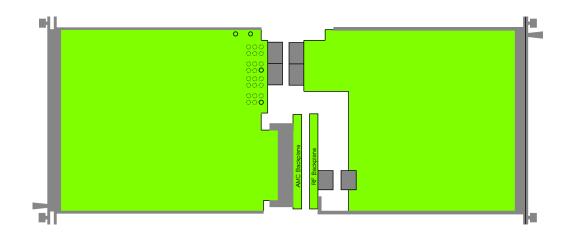


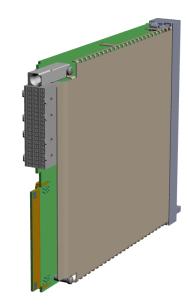
Standardization continued:

MTCA.4 Standardization activities

- > Definition of a RTM Auxiliary Backplane (MTCA.4.1)
 - Based on the LLRF backplane
 - Optional connector usage

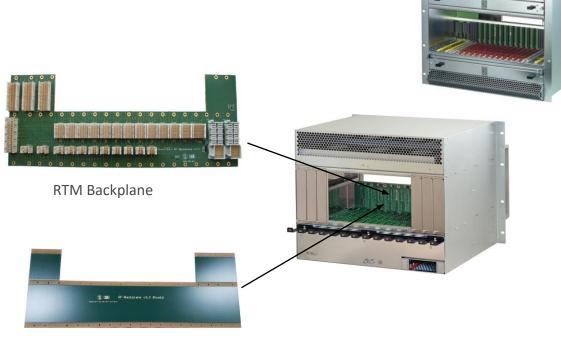
- Protective mechanical cover for AMC and RTM modules
 - Protective cover to mechanically protect components
 - For Side A and Side B

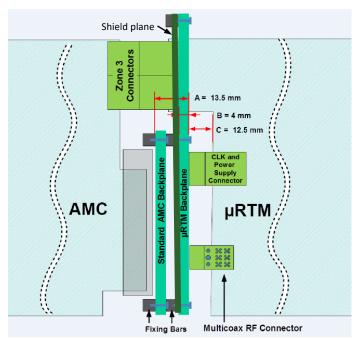






- > Auxiliary backplane for rear transition modules
- Rear power modules
- MCH Management Support & Extended Rear Transition Module (MCH-RTM)





Location for the RTM backplane in a MTCA.4 shelf

Dimension: Height: 159.5mm Width: 424.5mm Thickness: 2mm (backplane) + 2mm (shield extension)





MTCA.4.1 Rear Power Module

- The rear power module is connected with the RTM backplane and it provides additional power to the RTMs.
- > Output power: up to 600W
- Dimensions:
 - Double width, full-size but reduced depth due to the connector position on the RTM backplane
 - Depth: 185,85 mm distance the AMC backplane to the RTM backplane

MTCA.4.1 MCH-RTM

- > The MCH-RTM can contain CPU, storage and peripherals which safes space in the AMC area.
- > Dimensions: Double width, full-size, depth 185,85 mm





